

AMENDMENTS

In the Specification

Please replace the paragraph beginning at page 3, line 14, with the following rewritten paragraph:

-- Figs. 3a and 3b show the first embodiment of the present invention. The chip carrier plate 200 of the present invention comprises a base 201, a protruding face 202 and a receiving face 203. The protruding face 202 is disposed on the base 201. The receiving face 203 is formed on another side of the base 201 opposite to the protruding face 202. A plurality of recesses 210 is formed on the protruding face 202. Each recess 210 has a first spacer (first protrusion) 220 and a second spacer (second protrusion) 230 disposed on the bottom surface therein. --

Please replace the paragraph beginning at page 4, line 18, with the following rewritten paragraph:

-- Fig. 7 shows a second embodiment of the present invention, which has a third spacer 240, disposed between the first spacer 220 and the second spacer 230. The third spacer (third protrusion) 240 contacts the gold bumps 251 of the chip 250 to prevent deformation of chip 250.

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